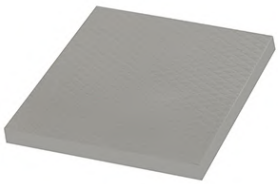
TP 200-S

Soft, Gap Filler Pad

TP 200-S gap filler pad, is key when your thermal needs begin to changed from design enhancement to thermal requirement. At 2.0 W/m.K, TP 200-S begins to add that extra thermal punch many designs require to keep specifications within thermal design targets.



Features and Benefits

- 2.0 W/m.K
- Ultra soft and highly compliant
- Naturally tacky, easing application
- High electrical insulation
- Good temperature resistance

Typical Applications

- Networking and Telecommunications
- IT: Notebooks, Tablets, Power Conversion
- Industrial: LEDs, Power Supplies and Conversion
- Automotive: Control Modules, Turbo Actuators
- Consumer Electronics: Gaming Systems, and LCDs

Typical Properties		
Attribute	**Value**	**Test Method**
	TP 200-S	-
Composition	Ceramic Filler + Silicone	-
Color	Grey	Visual
Thickness (mm)	0.7 to 12.0	ASTM D374
Density (g/cc)	2.82	ASTM D792
Hardness (Shore OO)	25(Thickness≤1.0 Shore OO 35)	ASTM D2240
Usage Temperature (°C)	- 40 to 150	–
Electrical		
Breakdown Voltage (kV/mm)	≥ 6.0	ASTM D149
Volume Resistivity (Ω.cm)	10^{13}	ASTM D257
Dielectric Constant	7.0	ASTM D150
Flammability	V-0	UL 94
Thermal		
Thermal Conductivity (W/m.K)	2.0	ISO 22007-2

Storage

Store in a cool, dry, well-ventilated place.

Shelf life

Shelf life of the product is 12 months after date of shipment

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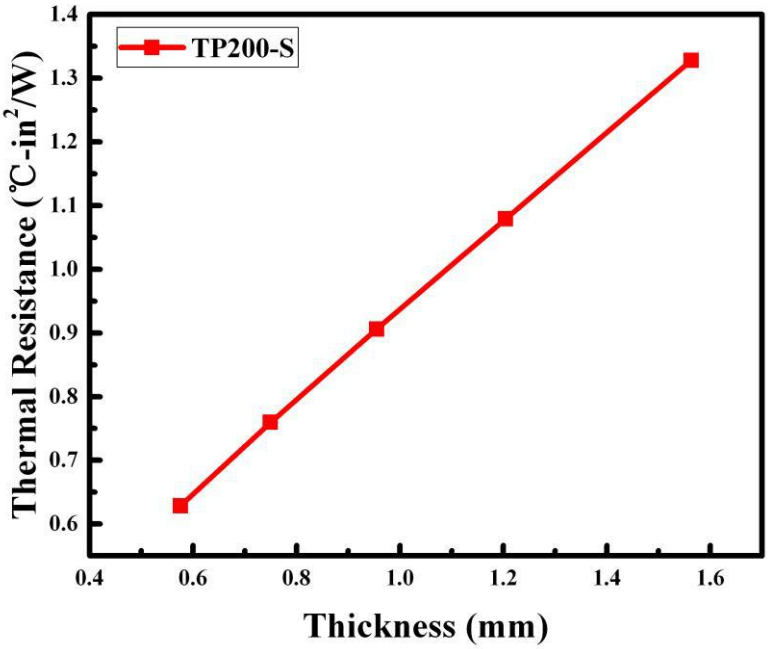
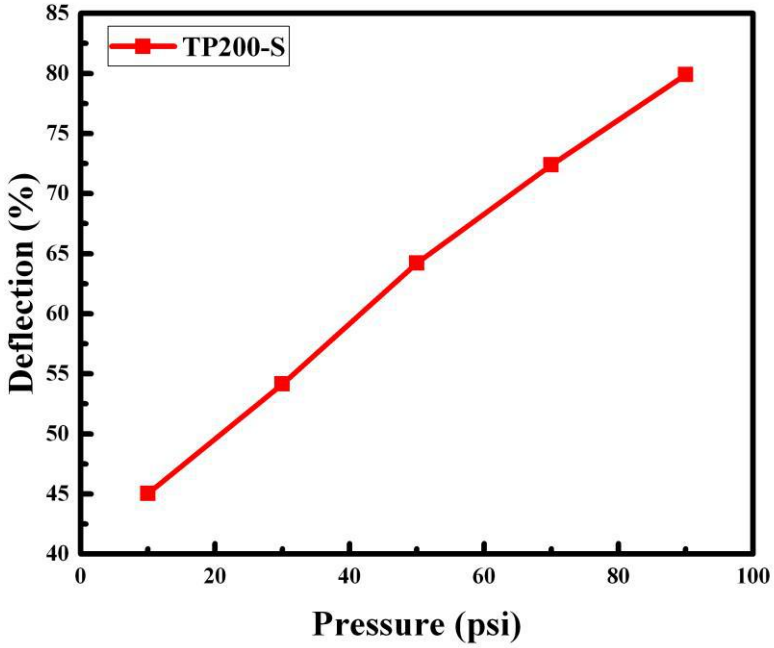
Thickness vs. Thermal Resistance

Reference only



Pressure vs. Deflection

Reference only



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